

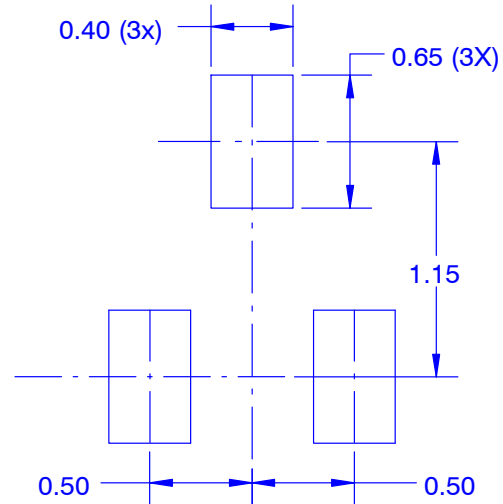
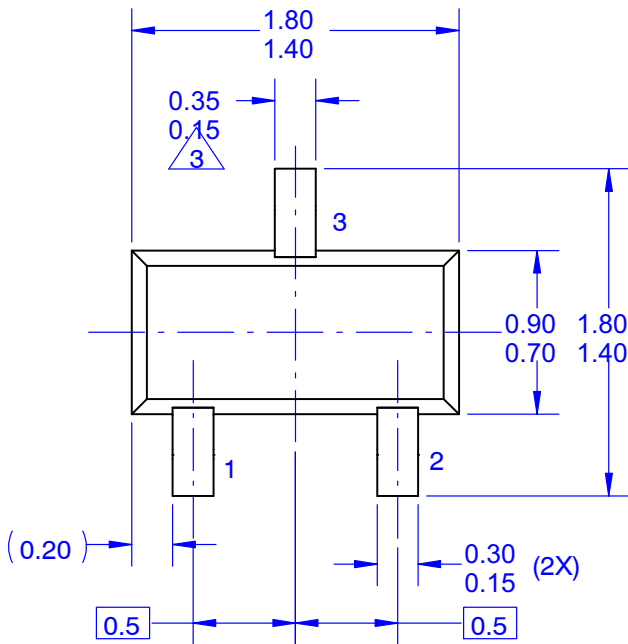
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

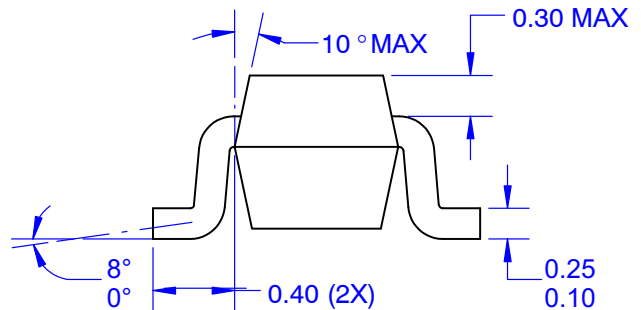
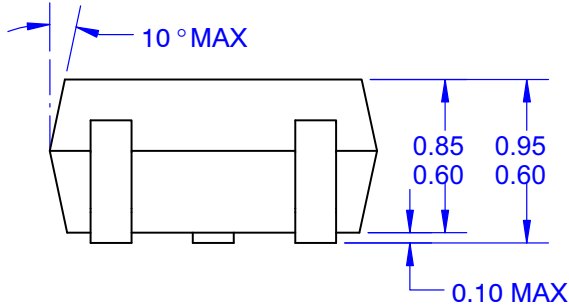


SOT-523
CASE 419BF
ISSUE O


DATE 31 AUG 2016




LAND PATTERN RECOMMENDATION



NOTES:

- A. REFERENCE TO EIAJ SC75 STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
-  DOES NOT COMPLY EIAJ SC75 STANDARD.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. LAND PATTERN RECOMMENDATION BASE FROM EIAJ STD.

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